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 U.S. Department of Commerce
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6-2404

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Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): In Gyun JEON Kwang Soo KIM Jin Su HAN		2. Name and address of receiving party(ies): Name: Dongbu Electronics Co., Ltd.	
Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		Internal Address: 891-10, Daechi-Dong Gangnam-Gu	
3. Nature of conveyance:		Street Address:	
<input checked="" type="checkbox"/> Assignment	<input type="checkbox"/> Merger	City: Seoul	
<input type="checkbox"/> Security Agreement	<input type="checkbox"/> Change of Name	State: Korea	Zip Code:
<input type="checkbox"/> Other: [Describe]		Additional name(s) & Address(es) attached?	
Execution Date: April 22, 2004 April 23, 2004		<input type="checkbox"/> Yes <input type="checkbox"/> No	
4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application:			
A. Patent Application Number(s): 10/747,302		B. Patent Number(s):	
Additional numbers attached?		<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
5. Name and address of party to whom correspondence concerning document should be mailed: Name: Qingyu Yin		6. Total number of applications and registrations involved: 1	
Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.		7. Total fee (37 CFR 3.41): \$40	
Street Address: 1300 I Street, N.W.		<input checked="" type="checkbox"/> Enclosed (Please charge deficiency to deposit account)	
City: Washington		<input type="checkbox"/> Authorized to be charged to deposit account	
State: D.C. Zip: 20005-3315		8. Deposit Account No.: 06-0916	
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.			
Kenneth M. Lesch		Signature: <i>Kenneth M. Lesch</i> Date: <i>June 24, 2004</i>	
Total number of pages including cover sheet, attachments and documents: 3			

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**PATENT
REEL: 015515 FRAME: 0213**

SOLE/JOINT INVENTION
(U.S. Rights Only)

ATTORNEY DOCKET NO. 08850-0005

A S S I G N M E N T

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

COMS Image Sensor and Method for Manufacturing the Same

for which I/WE executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on December 30, 2003
(Serial No. 10/747,302); and

WHEREAS, DONGBU ELECTRONICS CO., LTD., a
corporation of Republic of Korea,
whose post office address is: 891-10, Daechi-Dong, Gangnam-Gu,
Seoul, Republic of Korea

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

1. Full Name of Sole or first Assignor
In Gyun JEON

Address: 502-702, Hyundai-5-Cha Apartment, Daewol-Myun, Icheon-Si, Kyunggi-Do,

First Assignor's Signature: In Gyun JEON Republic of Korea

Date: April 23, 2004

2. Full Name of Second Assignor, if any
Kwang Soo KIM

Address: Eunsung Building, Sookwang-Ri, Sindoon-Myun, Icheon-Si, Kyunggi-Do, Republic of Korea

Second Assignor's Signature: Kwang Soo KIM

Date: April 22, 2004

3. Full Name of Third Assignor, if any
Jin Su HAN

Address: Eunsung Building, Sookwang-Ri, Sindoon-Myun, Icheon-Si, Kyunggi-Do, Republic of Korea

Third Assignor's Signature: Jin Su HAN

Date: April 23, 2004

4. Full Name of Fourth Assignor, if any

Address:

Fourth Assignor's Signature

Date:

5. Full Name of Fifth Assignor, if any

Address:

Second Assignor's Signature

Date:

6. Full Name of Sixth Assignor, if any

Address:

Sixth Assignor's Signature

Date:

7. Full Name of Seventh Assignor, if any

Address:

Seventh Assignor's Signature

Date:

8. Full Name of Eighth Assignor, if any

Address:

Eighth Assignor's Signature

Date: